

IEEE JRFID Special Issue on Printed RF

This special issue aims to highlight the advancements of additive manufacturing technology and its applications in the RF field. The scope includes, but is not limited to the following:

Materials for printed RF applications including: dielectric materials; conductive inks; semiconductive materials; tunable materials and biodegradable RF materials	Additive manufactured RFID antennas and chipless RFID
Additive manufacturing processes for RF applications	Additive manufactured reflective surfaces for beam shaping and steering
RF sensors for bio, chemical, physical applications	Integrated printed RF with radar and other testing/measurement systems
Additive manufactured RF antennas	Applications of printed RF devices

SUBMISSION GUIDELINES

When uploading your manuscript, please select the following TYPE: **“Printed RF”**.

If the manuscript is the extension of a conference paper, the following requirements must be accounted for:

1. In the manuscript, the conference paper must be listed as one of the references and clearly cited in the text. A pdf copy of the conference paper must also be submitted, as **Supplementary Material for Review but not for Publication**, since it will be transmitted to AE and reviewers.
2. The manuscript must be significantly extended beyond the scope of the conference paper in terms of the overall technical contents and research results (a similarity percent less than 30% is mandatory). The differences with respect to the conference paper must be properly discussed and highlighted through the text. Additionally, the authors must provide detailed information in the Cover Letter about how the manuscript is a technically extended version of the conference paper, and the Cover Letter will be transmitted to AE and reviewers.

The manuscript, together with the accompanying documents - **Cover Letter and IEEE Copyright Transfer Form (and conference paper, if the manuscript is its extension)** - must be submitted electronically through the [IEEE JRFID AUTHOR PORTAL SUBMISSION WEBSITE](https://journals.ieeeauthorcenter.ieee.org/), according to the format there available <https://journals.ieeeauthorcenter.ieee.org/>. Failure to follow above guidelines will result in the immediate return of the manuscript to the author(s) as an unacceptable submission. For any questions on the submission process, please contact the Editor-in-Chief of IEEE JRFID, Prof. Paolo Nepa (paolo.nepa@unipi.it) or the Guest Editors.

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SUBMISSION DEADLINE: ~~January 31, 2026~~ March 31, 2026

Submissions in advance with respect to the deadline are strongly encouraged since the accepted manuscripts will be published on IEEE Xplore and paginated within the Topic **“Printed RF”** as soon as the final files are submitted by the author(s).

About the Journal: IEEE Journal of Radio Frequency Identification is the flagship journal (Hybrid Open Access) of the IEEE CRFID. JRFID has achieved remarkable success and outstanding metrics, solidifying its position as a leading publication in the field of the technologies for communication, localization, wireless power transfer and sensing.

Most recent JRFID metrics: 2024 Impact Factor: **3.4**; 2024 Cite Score: **6.1**. JRFID has also excelled in publication timeliness (as from the IEEE PSPB report for Q1 2025): Average Weeks Submitted to First Decision: **5.2 weeks**; Average Weeks Submitted to Online Post: **12.5 weeks**.